



Product Change Notification

Change Notification #: 118490-00
Change Title: Select Intel® Optane™ SSD DC P4801X Series,
 PCN 118490-00, Label, Transport Media Label and Packaging Update
Date of Publication: September 14, 2021

Key Characteristics of the Change:
 Label, Transport Media

Forecasted Key Milestones:

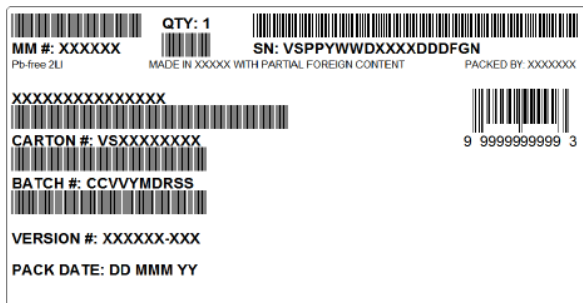
Date Customer Must be Ready to Receive Post-Conversion Material	October 14, 2021
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Description of Change to the Customer:

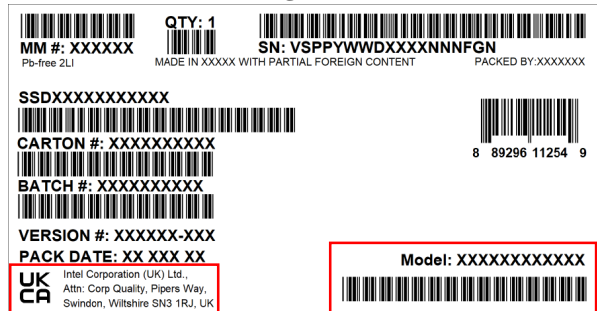
The Intel SKUs listed in the products affected table will have the following changes.

- Change 1: Generic MOQ1 Pizzabox label (add UKCA and Model)
- Change 2: Generic MOQ1 Disti box label
- Change 3: Packaging Update (All MM#'s EXCEPT FOR, 985978, 986008, 986009)

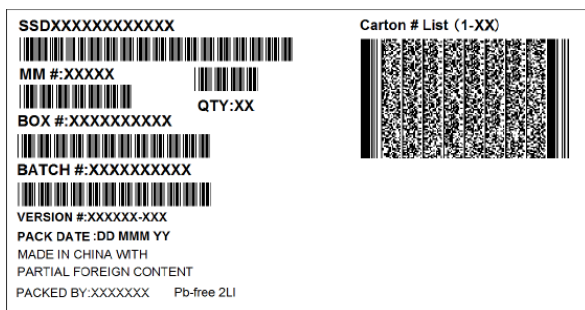
Change 1: Current



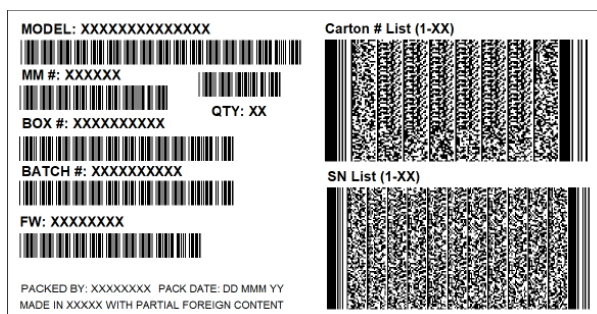
Change 1: New



Change 2: Current



Change 2: New



Change 3: Current Packaging

Change 3: New Packaging

EXCLUDING MM#'s, 985978, 986008, 986009)



Customer Impact of Change and Recommended Action:

There is no change to the form, fit, or function of the product. The change is only to the labels used in packaging.

Customers should be aware of the changes to the label and take appropriate actions to accommodate the changes and avoid impact to their process.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible. Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected/Intel Ordering Codes:

Marketing Name	Product Code	MM#
Intel® Optane™ SSD DC P4801X Series (375GB, M.2 110mm PCIe x4, 3D XPoint™, 60DWPD) Generic Single Pack	SSDPEL1K375GA01	958880
Intel® Optane™ SSD DC P4801X Series (100GB, M.2 110mm PCIe x4, 3D XPoint™, 60DWPD) Generic Single Pack	SSDPEL1K100GA01	964887
Intel® Optane™ SSD DC P4801X Series (200GB, M.2 110mm PCIe x4, 3D XPoint™, 60DWPD) Generic Single Pack	SSDPEL1K200GA01	964892
Intel® Optane™ SSD DC P4801X Series (100GB, M.2 110mm PCIe x4, 3D XPoint™, 60DWPD) with Heat Spreader, Generic Single Pack	SSDPEL1C100GA01	985978
Intel® Optane™ SSD DC P4801X Series (200GB, M.2 110mm PCIe x4, 3D XPoint™, 60DWPD) with Heat Spreader, Generic Single Pack	SSDPEL1C200GA01	986008
Intel® Optane™ SSD DC P4801X Series (375GB, M.2 110mm PCIe x4, 3D XPoint™, 60DWPD) with Heat Spreader, Generic Single Pack	SSDPEL1C375GA01	986009

PCN Revision History:

Date of Revision:

September 14, 2021

Revision Number:

00

Reason:

Originally Published PCN



Product Change Notification

118790-00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

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